



The CMS High Granularity Calorimeter for HL-LHC

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In this talk:

- Brief Introduction
 - Toward the upgrade of CMS for the HL-LHC era
- > The CMS Phase-II Endcap Calorimeter upgrade
 - Introduction to CMS Phase-II upgrade
- The HGCal detector
 - Layout, mechanics, read-out, electronics and performance
- The HGCal L1-Trigger
 - The HGCal L1-Trigger: hardware and software
- Plans and Conclusions



Introduction



Machine upgrade

 \rightarrow Luminosity needed to deliver the demanding physics program for Phase-2

Detector upgrade

- ➔ To maintain excellent performance in the harsh HL-LHC environment
- > Key role of the forward calorimeter
 - → SM and BSM searches, complementary to the tracker upgrade







HGCal General Layout



High Granularity sampling Calorimeter (HGCal)



Electromagnetic calorimeter (CE-E): Si, Cu & W & Pb absorbers, 28 layers, 25 X₀ & ~1.3λ Hadronic calorimeter (CE-E): Si & scintillator, steel absorbers, 24 layers, ~8.5λ





Mitigating radiation damage:

- > Mitigate leakage current noise \rightarrow cooled to -30°C (cooling fluid is CO₂)
- ➤ Mitigate signal loss → thinner sensors and higher bias voltage

Potential to use timing information to reject the PU:

Reach intrinsic time resolution of O(25ps)

Si Sensors:

- 3 different active thicknesses:
 (100, 200, 300) µm
- Thinnest sensors in the innermost region with smaller cell size (~0.5cm²)
- Smaller cells → less PU noise (less dose)





HGCal Mechanics



Mechanical Design:

- >CE-E: Pb+Cu absorber integrated into cassettes
- >CE-H: steel absorber, full disk + cassettes inserted between absorber

Layers structure:





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=2.9





- Each wafer (hexagons cut from 8" circular wafers) is made up of 432 (192) hexagonal 0.5 (1.0) cm² cells with 6 (3) readout chips
- 2 PCBs/layer: 1st PCB wire-bonded to Si sensor, Motherboard (2nd PCB)
- Data are transmitted by IpGBT links: ~8k links dedicated to trigger data and ~8k links dedicated to full resolution data. Try to reuse common developments as much as possible



~16000 LpGBT links for 25000 modules



HGCal Electronics



Need high dynamic range: from single MIPs (for calibration) up to TeV showers achieved using traditional ADC for the small signals and TOT for high signals



HGCal Offline Reconstruction

Sim PFClusters

Associated Hits

Particle Flow with HGCal

- > Combining all the information from the different CMS sub-systems to identify all the stable particles in the event
 - \rightarrow build complex objects like MET, Jet, Taus
- > Big challenge in PU200 environment
- > Matching between tracks and HGCal clusters, promising performance



Expected jet p_T resolution <20% for jet with $p_T > 20 \text{ GeV}$ (PU140)

°d_10.6 أي Jet p_T resolution uniform in eta if compared to the current Phase-I endcap calorimeter projection (aged+PU140)



0.2

-2

muon gun @PU = 35

Phase I 50 PU

Phase II 140 PU

0

Phase I Aged 140 PU

2

η^{GEN}

HGCal Offline Reconstruction



Timing information to mitigate the PU

- Possible to resolve the vertex position for neutral particles with ~1cm uncertainties → better particle ID, PU reduction and global event reco.
- > PU reduction by a factor x5-x6 if time resolution is O(20ps)





0.03

HGCal Test-beams



> Validate concept of hexagonal Si sensors and Geant4 simulation

> Used SKIROC2, developed for CALICE: 64 channels per chips, 2 chips/module



CMS L1-Trigger Phase-II Upgrade



The new L1-Trigger:

- ➤The CMS L1-Trigger system is required to select/reject each bx → First step of analysis
- ➤Time-multiplexed structure + tracker information + latest generation of FPGA + fast optical links → For the first time a particle flow reconstruction at L1 is possible
- > Change in maximum rate: from O(100kHz) \rightarrow O(1MHz) + fixed latency from 4µs to 12.5µs

HGCal L1-Trigger:

- > Trigger Cell (TC) = 4 or 9 hexagonal cells (48 per wafer)
- > The selected TC is used as input to back-end algorithms
 - ightarrow produce the trigger primitives to be sent to the correlator



HGCal Trigger Primitive Generator

CERN

Time-Multiplexed Two-stage architecture:

- Stage-1: Dynamical clustering techniques based on the Nearest Neighbour TCs to generate 2D-clusters in each HGCal trigger layer.
- Stage-2: Generation of 3D-clusters relying on the longitudinal development of the shower, exploiting the projected position of each 2D-cluster to identify its direction.
- >The Stage-1→Stage-2 data transmission is x24 time-multiplexed to allow all data from one endcap to be processed by one FPGA





HGC TP Algorithms



Performance – Stage-1/2 cluster and data-format

Number of 2D-cluster per each layer

>tt+PU200 event→max ~300 2D-clusters

Constraint: 4 links/board output from Stage-1 and max 96 total links input to the Stage-2

>24x Time-Multiplexed allows for an average cluster size up to 144b



Number of 3D-cluster per each endcap

>tt+PU200 event \rightarrow max ~200 3D-clusters with p_T>1.0 GeV

Define the bandwidth to the correlator: ~40 kbit/(endcap x bunch-crossing)











Conclusion



- The endcap calorimeters will be replaced with the HGCal to face the harsh radiation environment and the high PU scenario at HL-LHC era.
- Innovative solutions have been adopted to guarantee radiation hardness and high granularity (0.56–1.06 cm²) of the detector using Si sensors as well as large dynamic range (ADC+TOT), low power consumption and timing accuracy O(50)ps of the read-out chips
- The high granularity and longitudinal segmentation allow full exploitation of particle shower properties for offline object identification, that can also benefit from timing information to mitigate the PU contamination
- The HGCal L1-trigger represents a real challenge:
 - output at ~40MHz performing an impressive data reduction from 300Tb/s (HGCROC output) to ~2Tb/s (correlator input) in less than 5µs while preserving good object reconstruction performance
- Use of track info + high granularity + latest FPGA and fast optical links
 - > PF-based approaches exploitable at L1-trigger level for the first time.





- For HGCal trigger, a 2-staged time-multiplexed architecture is proposed as baseline and first results in hardware confirm its feasibility
- The testbeam in 2017 at CERN and FNAL with modified SKIROC2_CMS, HGROC ASIC are almost over but more testbeam are scheduled in 2018
- TDR expected for the end of the year + refining of the clustering and reconstruction algorithms (both for L1 and offline) will continue We are here 2015 2016 2017 2018 2019 2020 2021 2022 2023 2024 2025 2026 LS3 Engineering and Sensor Production HGCal Prototyping Pre-production **On-detector Electronics** F D Mechanics Production R Module Assembly Cassette Assembly Endcap Assembly Test Off-detector electronics

Many challenges ahead and short time for producing such a complex device:
→ we are progressing well and according to schedule

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Back-Up

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Physics goal for HL-LHC

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The scientific goals require:

> High efficiency on lepton/photon reconstruction > Low trigger threshold

→not to compromise EWK physics

> Jet energy resolution maintained at very high PU

≻High luminosity → high PU > High n-fluence \rightarrow degradation of PbWO₄ > Dose in forward region $\sim 3 \times 10^5$ Gy > High data rate to L1-trigger O(100 Tb/s)

Rare H-decays + SUSY + Dark Matter HL-LHC challenges:

Precision measurements of H-sector

- > W,Z trilinear and quadrilinear couplings
- > L_{inst} = 5x10³⁴ cm⁻²s⁻¹@13TeV > <Pile-Up (PU)>≤200 Exploit the LHC at very high luminosity:
- HL-LHC (2026-203X) specification:
- Η g coccoccocco





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Current Detector degradation

- Current endcap is made of PbWO₄ crystals
- Radiation damage results in deteriorated signal yield
 - Formation of colour centres that cause light absorption
 - Laser monitoring mitigates this but only to a certain point
 - Energy resolution constant term after 3000 fb⁻¹ expected to be ~9%







energy resolution after 3000fb⁻¹ for current EC

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HGCal Si-Sensor and Wafers

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Hexagonal geometry as largest tile-able polygon

- Hexagonal geometry as largest tile-able polygon
 - 6" and 8" sensors considered
 - Cell sizes of ~0.5 cm² and ~1 cm²
 - Cell capacitance of ~50 pF
 - Will most likely need n-on-p for inner layers
- Some design goals
 - 1kV sustainability to mitigate radiation damage
 - Four quadrants to study inter-cell gap distance and its influence on V_{bd}, C_{int} and CCE
- A few more details about those sensors
 - Active thickness by deep diffusion or thinning
 - Inner guard ring is grounded, outer guard ring is floating
 - Truncated tips, so called mouse bites, for module mounting
 - Calibration cells of smaller size for single MIP sensitivity at end of life



Hamamatsu 6" 128ch design



From TIPP-2017



HGCal Si-Sensor and Wafers





IV and CV example measurements done with probe card plus external switching unit



HGCal Si-Sensor and Wafers



From TIPP-2017

- Preliminary module design is as following
 - First, the sensor is glued unto W/Cu baseplate covered with Au/Kapton foil
 - Then, the readout PCB is glued unto the sensor
 - Wire bonds through holes in the PCB connect readout board to sensor cells
- Per hole in the PCB, we can connect to 3 cells compared to 4 with squares
 - Makes routing more difficult. Investigating sensor design features that could help.





readout PCB



wire bonds

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HGCal FE architecture





- Stringent requirements for Front-End Electronics
 - Low power (< 10 mW/ch for analog part) MIP: 10k 20k e- (1,5 3 fC)
 - Low noise (< 2000 e-, 0.35 fC)

 - High dynamic range: 0 10 pC
- - System on chip (digitization, processing...)
- Low noise (< 2000 e-, 0.35 fC)</th>System on chip (digitization, pro-High radiation (200 Mrad, 1016 N)High speed readout (5-10 Gb/s)
 - ~ 6.5 million channels
- Reusing standard HL-LHC electronics development (e.g. IpGBT)



HGCROC ADC/TOT



► Key issues to be studied

- Noise
- Resolution
- Linearity
- Stability
- Calibration
- Accuracy
- Crosstalk
- Radiation
- Timing
- Systematic effects
- Important feature
 - ADC / TOT switching



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Both DAQ and TPG require boards with high I/O and significant processing power

- Currently assume same hardware usable by both
- Working assumption:
 - ATCA format
 - ~100 F/O links up to 16 or 25 Gbit/s in and out
 - Ultrascale(+) FPGA(s) for processing

Per Endcap	#
LpGBT links	~ 5k
Boards Stage 1 (2D Clustering)	48
Boards Stage 2 (3D Clustering, assuming 24x TMUX)	24



2012 MP7 - 72 links in and out, each ~ 9 Gb/s

2016

MPUltra - up to 96 links in and out, each ~16 Gb/s

From EPS-2017

HGCal DAQ & TPG boards



CMS



Full Stat. !

• Estimation of the maximum number of 2D-clusters per layer:

- > Ttbar events from RelVal sample;
- s(pp) cross-section evaluated @sqrt(s)=14TeV PU=200;
- <u>/RelValTTbar 14TeV/CMSSW 9 0 0 pre4-</u> <u>PU25ns 90X upgrade2023 realistic v3 D4TPU200c2-v1/GEN-SIM-RECO</u>
- Nearest-Neighbors (NN) clustering with SE>5mip_T, TE>2mip_T (CMSSW)
- The following has been assumed:
 - Raw link speed = 16.4Gb/s;
 - > Link encoding = 64b/66b;
 - > NtwMaps = 1008 (x8b)

- <u>So far:</u> > <u>Tmux=24 works</u>, Traver, 19 is probably O
- <u>Tmux=18 is probably OK</u>,

Tmux=12 is probably not OK;

Трацу	Raw 2D-Cluster size [b]									
Tmux	64	80	96	112	128	144	160	176	192	208
12	122	134	143	152	161	170	186	195	206	213
18	84	93	99	104	111	117	128	135	144	148
24	73	78	81	87	91	95	103	105	111	113
	Dynamic Range									





NNC2d - TTbar+PU200 — High Stat.



	Number of seeds inside 2D-clusters								
	1	2	3	4	>=4				
[%]	87.72	9.39	1.86	0.54	1.03				





NNC2d - TTbar+PU200 – High Stat.

IMax==0 ? 64b : 64b+24b*(IMax+1)



- Calibration using single photon gun:
 - Cluster dedicated calibration starting from C2d energy

$$E_{\pi} = \sum_{i=0}^{layer} a_i d_{ie}$$

 Where d_{ie} are the energy deposits (in transverse mip – mipT) in the active layers, while the a_i are the coefficients to estimate. The RMS can be evaluated:

$$RMS^{2} = \frac{1}{N} \sum_{e=1}^{sample} \left(\sum_{i=0}^{layer} a_{i}d_{ie} - E_{Te}^{true} \right)$$

 Where T_e is the pion truth energy. If we minimize the RMS², the problem to find the a_i reduces to a linear algebra problem of a matrix inversion:

$$M \cdot a = v \Longrightarrow a = M^{-1} \cdot v$$

• Where M and v are thus defined as:

$$M_{ij} = \frac{\sum_{e=1}^{sample} d_{ie} d_{je}}{N} \qquad \qquad v_i = \frac{\sum_{e=0}^{sample} d_{ie} E_e^{true}}{N}$$



Estimation of the matrix element for photon clusters

- Single-photon pT=50GeV no-PU
- C3d+NNC2d-2D clustering with SE>5mip_T, TE>2mip_T (CMSSW_9_2_0_patch2)
- Energy encoding: 16b + Trunc: 0b
- > Most energetic C3d in a cone of ΔR =0.5 around the true photon



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Extraction of the calibration coefficients

All coefficients are positive → Next step: errors
 All layers in EE





Only trg-layers in EE









Deeper look to the coefficients:

- Comparison between coefficients values obtained using all the layers and only the trigger-layers
- The coefficients estimated using trg-layers assume larger values (~double), to take care for the deeper absorber between the two active layer considered.



Matrix Inversion Calibration - Tau 💬

Calibration Coefficients Shapes

- > Comparison with respect those obtained from photons and pion
- > Same clustering threshold for all physics objects (SE=2 mip_T and TE=2 mip_T)



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Matrix Inversion Calibration



- Application of the matrix inversion calibration coefficients
 - > Sample of $Z \rightarrow$ ee without PU
 - Compared with response obtained with the global scale factor cluster calibration





Tau clusters in HGCal



Once again... look to taus!

- Study of hadronic decay modes
- Low multeplicity colimated jets, involving more HGCal 3D-clusters
- Study the energy desity for tau-id @L1
- Dedicated calibration





mipT average 3D-cluster density

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